

REVISIONS

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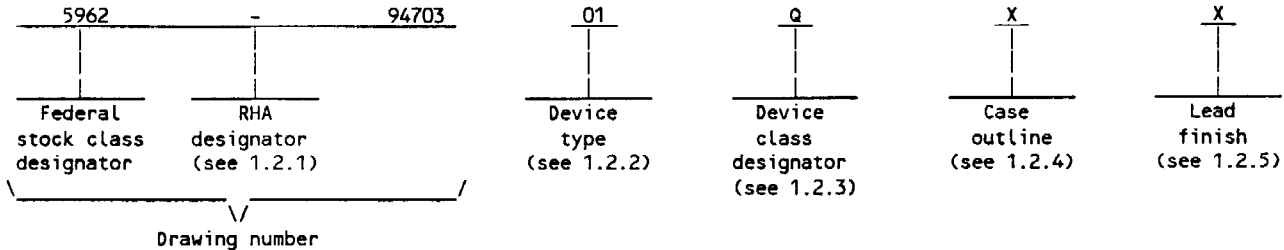
REV STATUS OF SHEETS	REV																			
	SHEET	1	2	3	4	5	6	7	8	9	10	11	12							

PMIC N/A	PREPARED BY Dan Wonnell	DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	
<p align="center">STANDARD MICROCIRCUIT DRAWING</p> THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE	CHECKED BY Sandra Rooney		
	APPROVED BY Michael A. Frye	SIZE CAGE CODE 5962-94703 A 67268	
	DRAWING APPROVAL DATE 94-11-04	SHEET 1 OF 12	
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1. SCOPE

1.1 Scope. This drawing forms a part of a one part - one part number documentation system (see 6.6 herein). Two product assurance classes consisting of military high reliability (device classes Q and M) and space application (device class V), and a choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). Device class M microcircuits represent non-JAN class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices". When available, a choice of Radiation Hardness Assurance (RHA) Levels are reflected in the PIN.

1.2 PIN. The PIN shall be as shown in the following example:



1.2.1 RHA designator. Device class M RHA marked devices shall meet the MIL-I-38535 appendix A specified RHA levels and shall be marked with the appropriate RHA designator. Device classes Q and V RHA marked devices shall meet the MIL-I-38535 specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) shall identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	AD9058T	Dual 8-bit analog-to-digital converter

1.2.3 Device class designator. The device class designator shall be a single letter identifying the product assurance level as follows:

<u>Device class</u>	<u>Device requirements documentation</u>
M	Vendor self-certification to the requirements for non-JAN class B microcircuits in accordance with 1.2.1 of MIL-STD-883
Q or V	Certification and qualification to MIL-I-38535

1.2.4 Case outline(s). The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
X	GDIP1-T48 or CDIP2-T48	48	dual-in-line
Y	see figure 1	44	"J" Lead chip carrier

1.2.5 Lead finish. The lead finish shall be as specified in MIL-STD-883 (see 3.1 herein) for class M or MIL-I-38535 for classes Q and V. Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

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1.3 Absolute maximum ratings. 1/

Positive supply voltage (+V _S)	+6 V dc
Negative supply voltage (-V _S)	+0.8 V dc to -6 V dc
Analog input	-1.5 V dc to +2.5 V dc
Digital inputs	-0.5 V dc to +V _S
Digital output current	20 mA
Voltage reference current	53 mA
Positive voltage reference (+V _{REF})	+2.5 V dc
Negative voltage reference (-V _{REF})	-1.5 V dc
Junction temperature (T _J)	+175°C
Thermal resistance, junction-to-ambient (θ _{JA}):	
Case outline X	40°C/W
Case outline Y	86.4°C/W
Thermal resistance, junction-to-case (θ _{JC}):	
Case outline X	12°C/W
Case outline Y	24.9°C/W
Case storage temperature range	-65°C to +150°C
Lead temperature (soldering 10 sec.)	+300°C

1.4 Recommended operating conditions.

Case operating temperature range (T _C)	-55°C to +125°C
Supply voltage (±V _S)	±5 V dc
Analog input voltage range (A _{IN})	0 V dc to 2 V dc

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, bulletin, and handbook. Unless otherwise specified, the following specification, standards, bulletin, and handbook of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-I-38535 - Integrated Circuits, Manufacturing, General Specification for.

STANDARDS

MILITARY

- MIL-STD-883 - Test Methods and Procedures for Microelectronics.
- MIL-STD-973 - Configuration Management.
- MIL-STD-1835 - Microcircuit Case Outlines.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

HANDBOOK

MILITARY

MIL-HDBK-780 - Standardized Military Drawings.

1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability. For applications in which +V_S may be applied before -V_S, or +V_S current is not limited to 500 mA, a reverse-biased clamping diode should be inserted between ground and -V_S to prevent destructive latch up.

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(Copies of the specification, standards, bulletin, and handbook required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device class M shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein. The individual item requirements for device classes Q and V shall be in accordance with MIL-I-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not effect the form, fit, or function as described herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-STD-883 (see 3.1 herein) for device class M and MIL-I-38535 for device classes Q and V and herein.

3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 and figure 1 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full case operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. Marking for device class M shall be in accordance with MIL-STD-883 (see 3.1 herein). In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103. Marking for device classes Q and V shall be in accordance with MIL-I-38535.

3.5.1 Certification/compliance mark. The compliance mark for device class M shall be a "C" as required in MIL-STD-883 (see 3.1 herein). The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-I-38535.

3.6 Certificate of compliance. For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.7.2 herein). For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.7.1 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device class M, the requirements of MIL-STD-883 (see 3.1 herein), or for device classes Q and V, the requirements of MIL-I-38535 and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required for device class M in MIL-STD-883 (see 3.1 herein) or for device classes Q and V in MIL-I-38535 shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change for device class M. For device class M, notification to DESC-EC of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change as defined in MIL-STD-973.

3.9 Verification and review for device class M. For device class M, DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 Microcircuit group assignment for device class M. Device class M devices covered by this drawing shall be in microcircuit group number 57 (see MIL-I-38535, appendix A).

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. For device class M, sampling and inspection procedures shall be in accordance with MIL-STD-883 (see 3.1 herein). For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-I-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not effect the form, fit, or function as described herein.

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C unless otherwise specified 1/	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Differential nonlinearity	DNL		1	01		0.5	LSB
			2, 3			1.0	
Integral nonlinearity	INL		1	01		1.0	LSB
			2, 3			1.25	
Input bias current	I _B		1	01		170	μA
			2, 3			340	
Input resistance	R _I		1	01	12		kΩ
Input capacitance 2/	C _I	A _{IN} = 0 V, see 4.4.1c	4	01		15	pF
Reference ladder resistance	R _{RL}		1	01	120	220	Ω
			2, 3		80	270	
Reference ladder offset (top)	O _{RLT}		1	01		16	mV
			2, 3			24	
Reference ladder offset (bottom)	O _{RLB}		1	01		23	mV
			2, 3			33	
Reference voltage	V _{REF}		1	01	1.95	2.2	V
			2, 3		1.90	2.25	
Power supply rejection ratio	PSRR		1	01		25	mV/V
Conversion rate	CONV		4	01	50		MspS
Output delay (valid)	t _V	2 kΩ pulldowns	9	01	5		ns
Aperature delay 2/	t _A		9	01	0.1	1.5	ns
Aperature delay matching 2/	t _{AM}		9	01		0.5	ns
Propagation delay	t _{PD}	2 kΩ pulldowns	9	01		19	ns

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - continued.

Test	Symbol	Conditions -55°C ≤ T _c ≤ +125°C unless otherwise specified 1/		Group A subgroups	Device type	Limits		Unit
						Min	Max	
Encode pulse voltage (high)	V _{EH}			1, 2, 3	01	2.0		v
Encode pulse voltage (low)	V _{EL}			1, 2, 3	01		0.8	v
Encode pulse current (high)	I _{EH}			1, 2, 3	01		300	μA
Encode pulse current (low)	I _{EL}			1, 2, 3	01		500	μA
Effective number of bits	ENOB	A _{IN} = 2.3 MHz 3/	for case X	4	01	7.0		Bits
			for case Y			7.2		
		A _{IN} = 10.3 MHz 3/	for case X			6.8		
			for case Y			7.1		
Signal-to-noise ratio	SNR	A _{IN} = 2.3 MHz 3/	for case X	4	01	44		dB
			for case Y			45		
		A _{IN} = 10.3 MHz 3/	for case X			43		
			for case Y			44		
		A _{IN} = 2.3 MHz 3/ 50 Msps encode	for case X			41		
			for case Y			42		
		A _{IN} = 2.3 MHz 3/ 8 ns HIGH encode	for case X			44		
			for case Y			45		
		A _{IN} = 2.3 MHz 3/ 8 ns LOW encode	for case X			44		
			for case Y			45		
2nd harmonic distortion	HD ₂	A _{IN} = 2.3, 10.3 MHz		4	01	48		dBc
3rd harmonic distortion	HD ₃	A _{IN} = 2.3, 10.3 MHz		4	01	50		dBc
Crosstalk rejection 2/	CR	A _{IN} = 2.3, 3.5 MHz, 40 Msps		4	01	48		dBc

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C unless otherwise specified 1/	Group A subgroups	Device type	Limits		Unit
					Min	Max	
High level output voltage	V _{OH}		1, 2, 3	01	2.4		V
Low level output voltage	V _{OL}		1, 2, 3	01		0.4	V
Positive supply current	+I _S		1, 2, 3	01		167	mA
Negative supply current	-I _S		1, 2, 3	01		41	mA
Power dissipation 4/	P _D		1, 2, 3	01		1040	mW

1/ ±V_S = ±5 V; +V_{REF} = +2 V (internal); -V_{REF} = GROUND; ENCODE = 40 Msps; A_{IN} = 0 V to +2 V.

2/ Test limit is characterized and is guaranteed at T_C = +25°C but not tested.

3/ Measured with analog input signal 1 dB below full scale at specified frequency.

4/ Test limit applies to both A/D's and includes ladder dissipation.

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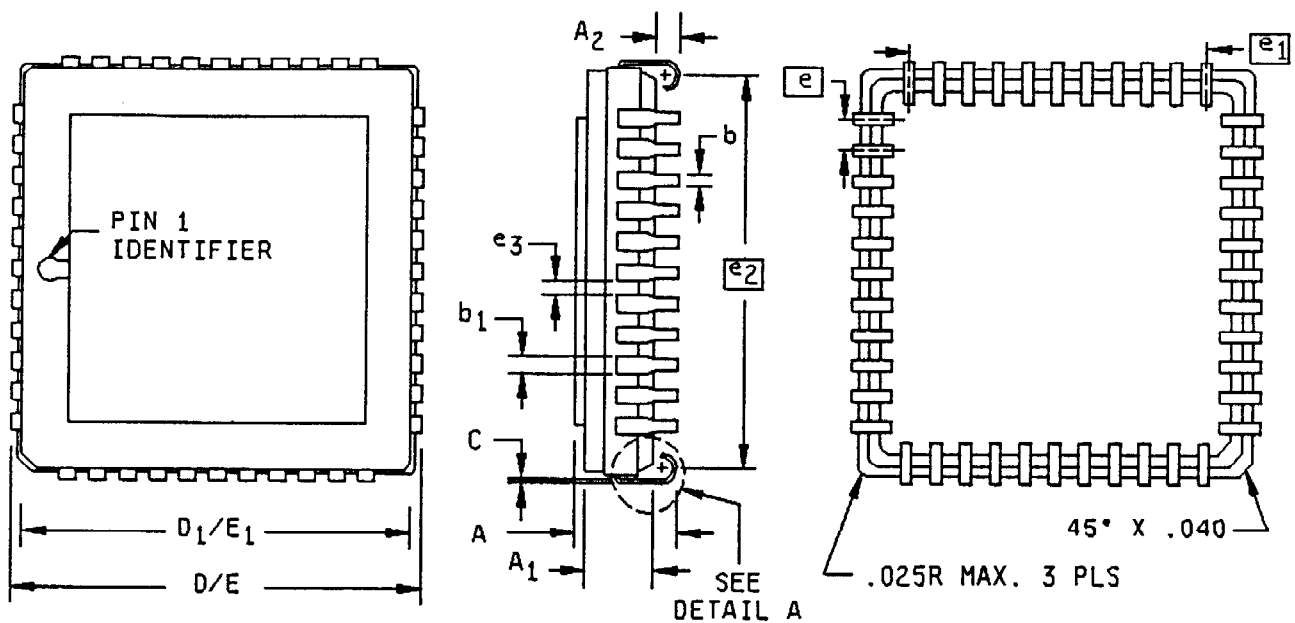
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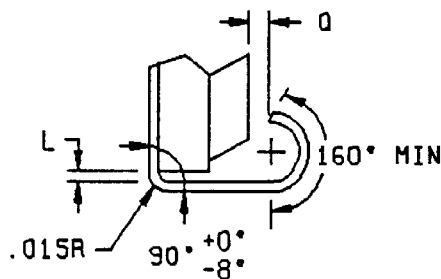
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TOP VIEW

SIDE VIEW

BOTTOM VIEW



DETAIL A

Symbol	Inches		Millimeters	
	Min	Max	Min	Max
A		.171		4.34
A ₁	.092	.112	2.34	2.84
A ₂	.034	.044	.86	1.12
b	.017	.021	.43	.53
b ₁	.026	.030	.66	.76
c	.0054	.0066	.14	.17
D/E	.678	.698	17.22	17.73

Symbol	Inches		Millimeters	
	Min	Max	Min	Max
D ₁ /E ₁	.642	.658	16.31	16.71
e	.050 BSC		1.27 BSC	
e ₁	.500 BSC		12.70 BSC	
e ₂	.610	.630	12.49	16.00
e ₃	.019	.025	4.83	6.35
L	.010		.25	
q	.005 REF		.13 REF	

FIGURE 1. Case outline Y.

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Device type	01	
Case outline	X	Y
Terminal number	Terminal symbol	
1	GROUND	COMP
2	ENCODE	+V _{INT}
3	+V _S	+V _{REF}
4	GROUND	GROUND
5	-V _{REF}	+V _S
6	-V _S	A _{IN}
7	NC	-V _S
8	A _{IN}	-V _{REF}
9	+V _S	+V _S
10	GROUND	ENCODE
11	+V _{REF}	D ₇ (MSB)
12	COMP	D ₆
13	+V _{INT}	D ₅
14	+V _{REF}	D ₄
15	GROUND	D ₃
16	+V _S	D ₂
17	A _{IN}	D ₁
18	NC	D ₀ (LSB)
19	-V _S	GROUND
20	-V _{REF}	-V _S
21	GROUND	GROUND
22	+V _S	+V _S
23	ENCODE	NC
24	GROUND	+V _S
25	D ₇ (MSB)	GROUND
26	D ₆	-V _S

Device type	01	
Case outline	X	Y
Terminal number	Terminal symbol	
27	D ₅	GROUND
28	D ₄	D ₀ (LSB)
29	D ₃	D ₁
30	D ₂	D ₂
31	D ₁	D ₃
32	D ₀ (LSB)	D ₄
33	GROUND	D ₅
34	-V _S	D ₆
35	GROUND	D ₇ (MSB)
36	+V _S	ENCODE
37	+V _S	+V _S
38	GROUND	-V _{REF}
39	-V _S	-V _S
40	GROUND	A _{IN}
41	D ₀ (LSB)	+V _S
42	D ₁	GROUND
43	D ₂	+V _{REF}
44	D ₃	NC
45	D ₄	- - -
46	D ₅	- - -
47	D ₆	- - -
48	D ₇	- - -

FIGURE 2. Terminal connections.

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4.2 Screening. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. For device classes Q and V, screening shall be in accordance with MIL-I-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection.

4.2.1 Additional criteria for device class M.

- a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.
 - (2) $T_A = +125^\circ\text{C}$, minimum.
- b. Interim and final electrical test parameters shall be as specified in table II herein.

4.2.2 Additional criteria for device classes Q and V.

- a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-I-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-I-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.
- b. Interim and final electrical test parameters shall be as specified in table II herein.
- c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in appendix B of MIL-I-38535.

4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-I-38535. Inspections to be performed shall be those specified in MIL-I-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Quality conformance inspection for device class M shall be in accordance with MIL-STD-883 (see 3.1 herein) and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4). Technology conformance inspection for classes Q and V shall be in accordance with MIL-I-38535 including groups A, B, C, D, and E inspections and as specified herein except where option 2 of MIL-I-38535 permits alternate in-line control testing.

4.4.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 5, 6, 7, 8, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroup 4 (C_T measurement) shall be measured only for the initial test and after process or design changes which may affect input capacitance.

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table II herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- a. Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005.
- b. $T_A = +125^\circ\text{C}$, minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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TABLE II. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, TM 5005, table I)	Subgroups (in accordance with MIL-I-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	1	1	1
Final electrical parameters (see 4.2)	<u>1/</u> 1, 2, 3, 4, 9	<u>1/</u> 1, 2, 3, 4, 9	<u>1/</u> 1, 2, 3, 4, 9
Group A test requirements (see 4.4)	1, 2, 3, 4, 9	1, 2, 3, 4, 9	1, 2, 3, 4, 9
Group C end-point electrical parameters (see 4.4)	1	1	1, 2, 3, 4, 9
Group D end-point electrical parameters (see 4.4)	1	1	1
Group E end-point electrical parameters (see 4.4)	---	---	---

1/ PDA applies to subgroup 1.

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-I-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB, in accordance with MIL-I-38535, and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table II herein.

4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels for device classes Q and V shall be M, D, R, and H and for device class M shall be M and D.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-I-38535, appendix A, for the RHA level being tested. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-I-38535 for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at $T_A = +25^\circ\text{C} \pm 5^\circ\text{C}$, after exposure, to the subgroups specified in table II herein.
- c. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

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5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-STD-883 (see 3.1 herein) for device class M and MIL-I-38535 for device classes Q and V.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.1.2 Substitutability. Device class Q devices will replace device class M devices.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and which SMD's are applicable to that system. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.

6.4 Comments. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444-5270, or telephone (513) 296-5377.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-I-38535 and MIL-STD-1331.

6.6 One part - one part number system. The one part - one part number system described below has been developed to allow for transitions between identical generic devices covered by the three major microcircuit requirements documents (MIL-H-38534, MIL-I-38535, and 1.2.1 of MIL-STD-883) without the necessity for the generation of unique PIN's. The three military requirements documents represent different class levels, and previously when a device manufacturer upgraded military product from one class level to another, the benefits of the upgraded product were unavailable to the Original Equipment Manufacturer (OEM), that was contractually locked into the original unique PIN. By establishing a one part number system covering all three documents, the OEM can acquire to the highest class level available for a given generic device to meet system needs without modifying the original contract parts selection criteria.

<u>Military documentation format</u>	<u>Example PIN under new system</u>	<u>Manufacturing source listing</u>	<u>Document listing</u>
New MIL-H-38534 Standard Microcircuit Drawings	5962-XXXXXZZ(H or K)YY	QML-38534	MIL-BUL-103
New MIL-I-38535 Standard Microcircuit Drawings	5962-XXXXXZZ(Q or V)YY	QML-38535	MIL-BUL-103
New 1.2.1 of MIL-STD-883 Standard Microcircuit Drawings	5962-XXXXXZZ(M)YY	MIL-BUL-103	MIL-BUL-103

6.7 Sources of supply.

6.7.1 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DESC-EC and have agreed to this drawing.

6.7.2 Approved sources of supply for device class M. Approved sources of supply for class M are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-94703
		REVISION LEVEL	SHEET 12

STANDARD MICROCIRCUIT DRAWING SOURCE APPROVAL BULLETIN

DATE: 94-11-04

Approved sources of supply for SMD 5962-94703 are listed below for immediate acquisition only and shall be added to MIL-BUL-103 during the next revision. MIL-BUL-103 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DESC-EC. This bulletin is superseded by the next dated revision of MIL-BUL-103.

Standard microcircuit drawing PIN	Vendor CAGE number	Vendor similar PIN ^{1/}
5962-9470301MXX	34031	AD9058TD/883B
5962-9470301MYX	34031	AD9058TJ/883B

^{1/} Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE
number

34031

Vendor name
and address

Analog Devices Computer Labs
7910 Triad Center Drive
Greensboro, NC 27409-9605

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in this information bulletin.